



Material Content Data Sheet



Sales Product Name				TDA21231		Issued		1. August 2018	
MA#				MA001620886					
Package				PG-IQFN-31-2		Weight*		72.91 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.540	2.11	2.11	21120	21120	
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.00		48		
	non noble metal	zinc	7440-66-6	0.014	0.02		191		
	non noble metal	iron	7439-89-6	0.279	0.38		3822		
wire	non noble metal	copper	7440-50-8	11.316	15.52	15.92	155201	159262	
	non noble metal	copper	7440-50-8	0.099	0.14	0.14	1352	1352	
	encapsulation	organic material	carbon black	1333-86-4	0.059	0.08		814	
	plastics	epoxy resin	-	3.055	4.19		41900		
	inorganic material	silicondioxide	60676-86-0	26.546	36.42	40.69	364086	406800	
leadfinish	non noble metal	tin	7440-31-5	0.986	1.35	1.35	13530	13530	
plating	noble metal	silver	7440-22-4	0.054	0.07	0.07	737	737	
glue	plastics	epoxy resin	-	0.088	0.12		1212		
	noble metal	silver	7440-22-4	0.265	0.36	0.48	3636	4848	
solder	noble metal	silver	7440-22-4	0.037	0.05		502		
	non noble metal	tin	7440-31-5	0.073	0.10		1004		
	non noble metal	lead	7439-92-1	1.354	1.86	2.01	18575	20081	
heatspreader	inorganic material	phosphorus	7723-14-0	0.005	0.01		73		
	non noble metal	zinc	7440-66-6	0.021	0.03		291		
	non noble metal	iron	7439-89-6	0.424	0.58		5817		
	non noble metal	copper	7440-50-8	17.220	23.62	24.24	236177	242358	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.003	0.00		39		
	non noble metal	zinc	7440-66-6	0.011	0.02		156		
	non noble metal	iron	7439-89-6	0.227	0.31		3118		
	non noble metal	copper	7440-50-8	9.230	12.66	12.99	126599	129912	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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